a first multiplicity of said means for capacitively signaling between said chip and said substrate occupies a first area at a first pitch,

a second multiplicity of means for conductively signaling occupies a second area of said substrate at a second pitch,

a multiplicity of said transmission lines connects said first and second areas, and

said second area is larger than said first area.

214. A modular electronic system as defined in claim 210 wherein

a first multiplicity of said means for capacitively signaling between said chip and said substrate occupies a first area at a first pitch,

a second multiplicity of means for conductively signaling occupies a second area of said substrate at a second pitch,

a multiplicity of said transmission lines connects said first and second areas, and

said second pitch is larger than said first pitch.

215. A modular electronic system as defined in claim 210 wherein

a first multiplicity of said means for capacitively signaling between said chip and said substrate occupies a first area at a first pitch,

a second multiplicity of means for capacitively signaling occupies a second area of said substrate at a second pitch,

a multiplicity of said transmission lines connects said first and second areas, and

said second area is larger than said first area.

216. A modular electronic system as defined in claim 210 wherein

a first multiplicity of said means for capacitively signaling between said chip and said substrate occupies a first area at a first pitch,

a second multiplicity of means for capacitively signaling occupies a second area of said substrate at a second pitch,

a multiplicity of said transmission lines connects said first and second areas, and

said second pitch is larger than said first pitch.

217. A modular electronic system as defined in claim 102 including further paired half-capacitors such that said capacitive signal path is distributed among multiple capacitors.

218. A modular electronic system as defined in claim 102 wherein said first module is positioned relative to said second module by motion transverse to said capacitive signal path transverse to said conductive connection.

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219. A modular electronic system as defined in claim 102 wherein said second module is a cable, said cable including at least one non-coaxial wire.

220. A modular electronic system as defined in claim 102 wherein said first nodule further includes a transmission line that is connected to a plurality of transmission lines.

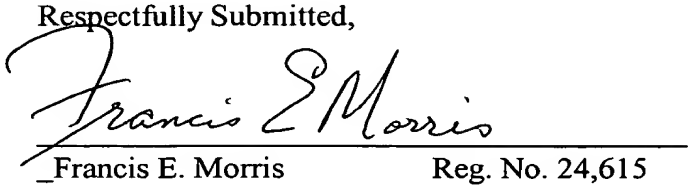
221. A modular electronic system as defined in claim 102 further comprising means for varying the admittance of said capacitive signal path by changing the effective area of overlap between said half-capacitors.

222. A modular electronic system as defined in claim 221 wherein said means for varying the admittance includes mechanical devices.

REMARKS

The above claims are all dependent on allowed claims. Accordingly, entry of this amendment at this time is appropriate.

Respectfully Submitted,



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